

*AS*

Replace the paragraph at page 13, lines 12-23 with the following:

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-- In addition to the strong bond formed between target 50 and backing plate 60 of assembly 70, a grain size of target 50 is preferably below 100 microns, more preferably from about 30 to less than 100 microns, and more preferably below about 50 microns after the diffusion bonding. Specifically, a predominate portion (i.e., more than 50%) of the grains in target 50 will preferably have a maximum dimension of less than 100 microns, more preferably from about 30 microns to less than 100 microns, and more preferably less than about 50 microns. In particular embodiments, an entirety of the grains in target 50 have a maximum dimension of less than 100 microns, more preferably from about 30 microns to less than 100 microns, and more preferably less than about 50 microns. --

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